

Electronic Patent Application Fee Transmittal

Application Number:	10663967
Filing Date:	16-Sep-2003
Title of Invention:	METHODS OF FABRICATING INTEGRATED CIRCUIT DEVICES HAVING FUSE STRUCTURES INCLUDING BUFFER LAYERS
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Filer:	Elizabeth A. Stanek/Erin Dutton
Attorney Docket Number:	5649-1161

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700